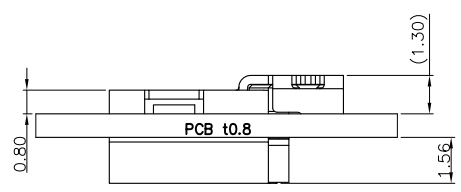
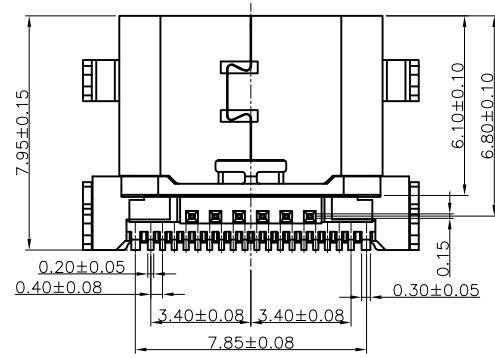
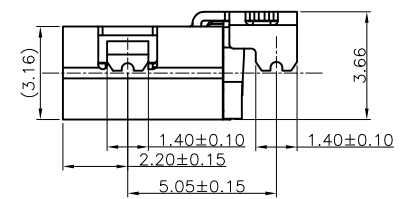
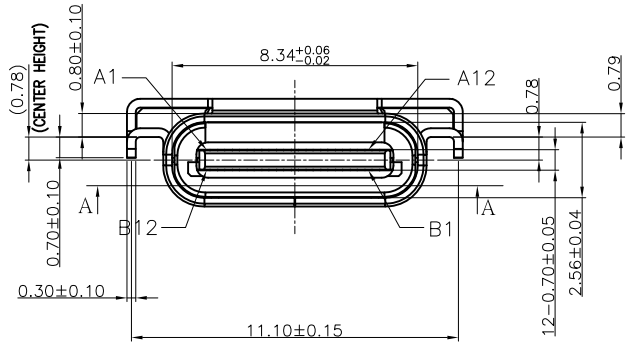
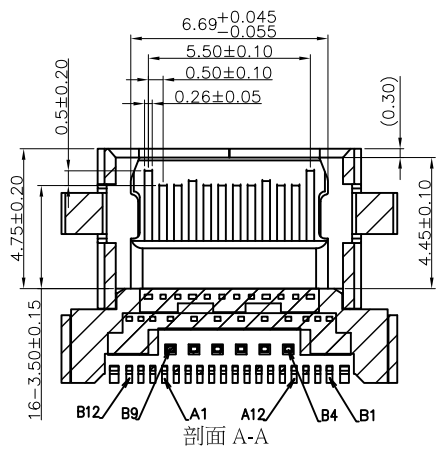
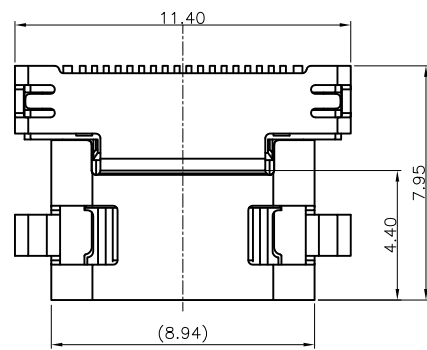
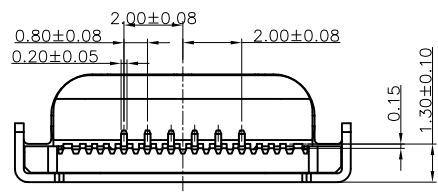


REV	ECN No.	DATE	REMARK
A	NEW	2021.08.12	NEW RELEASE



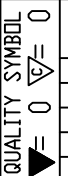
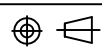
MOUNTING CONDITION (REF.)



- NOTES:
- MATERIAL:
 - MOLDING: LCP UL94 V-0
 - CONTACT: COPPER ALLOY
 - GOLD PLATED 1U Min ON CONTACT AREA, GOLD FLASH (LEAD FREE) ON SOLDER AREA.
 - SHELL: SUS304-H,T=0.30±0.03mm
 - 50u" NICKEL PLATING OVER ALL.
 - SHILD: SUS304-H,T=0.12±0.03mm
 - MECHANICAL:
 - INSERTION: 5~20N.
 - EXTRACTION: 8~20N.
 - DURABILITY: 10000 CYCLES
 - ELECTRICAL:
 - CURRENT: 5A MIN FOR VBUS; 0.25A MIN FOR OTHER.
 - VOLTAGE: 5VAC MAX
 - WITHSTANDING VOLTAGE: 100V AC.
 - CONTACT RESISTANCE: 40mΩ MAX.
 - INSULATION RESISTANCE: 100MΩ MIN.
 - ENVIRONMENTAL
 - TEMPERATURE RANGE: -30°C TO +80°C

5. PART NUMBER CODE:
 CF 3 24 - 019 S L B XX R - 75
 (1)(2) (3)(4)(5)(6)

- 产品型号: 3:沉板式
- Pin No.: 24:24Pin
- HOUSING MATERIALS: L:LCP
- HOUSING COLOR: B:BLACK
- CONTACTS PLATED: 01:接触镀金1u",焊接区G/F
- PACKING OPTIONS: R:TAPE & REEL

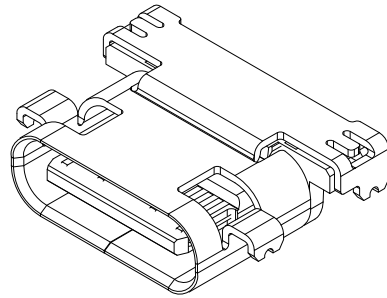
PART NO.: SEE THE PART NUMBER CODE		GOLDCONN TECHNOLOGIES COMPANY LIMITED		DRAWN BY SAM	DATE 2021.08.12
QUALITY SYMBOL 		GENERAL TOLERANCES (UNLESS SPECIFIED) X.XXXXX ± --- X.XXX ± 0.10 X.XX ± 0.25 X.X ± 0.30 ANGULAR ± ---		TITLE USB 3.1 C TYPE FEMALE SINK CH0.78 沉板2.36 SHORT SMT+DIP L 7.95	
		DWG.NO. CF324-019-75		SHEET NO. 1 OF 2	
DIMENSION STYLE MM ONLY		DESIGN UNITS METRIC		SCALE 1:1	
				APPROVED BY JACKY	
				DATE 2021.08.12	
 THIRD ANGLE PROJECTION					

RoHS Compliant



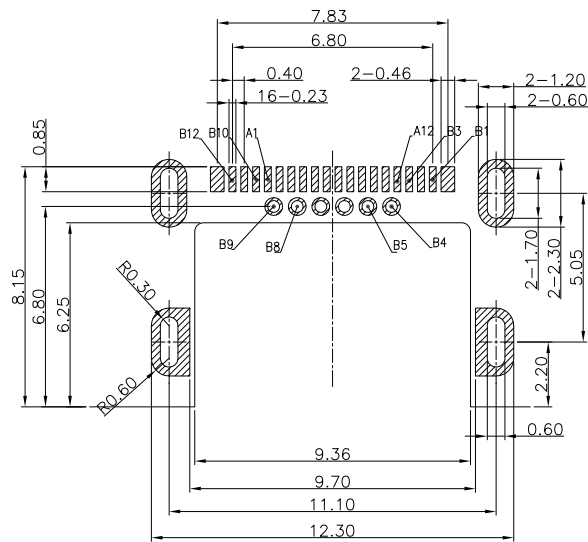
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO ZDT TECHNOLOGY, AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

REV	ECN No.	DATE	REMARK
A	NEW	2021.08.12	NEW RELEASE



USB TYPE-C FULL-FEATURED RECEPTACLE INTERFACE PIN ASSIGNMENTS

PIN	Signal Name	Description	PIN	Signal Name	Description
A1	GND	Ground return	B12	GND	Ground return
A2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of first SuperSpeed RX differential pair
A3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of first SuperSpeed RX differential pair
A4	VBUS	Bus Power	B9	VBUS	Bus Power
A5	CC1	Configuration Channel	B8	SBU2	Sideband Use (SBU)
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A8	SBU1	Sideband Use (SBU)	B5	CC2	Configuraaion Channel
A9	VBUS	Bus Power	B4	VBUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B3	SSTXn2	Negative half of second SuperSpeed TX differential pair
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B2	SSTXp2	Positive half of second SuperSpeed TX differential pair
A12	GND	Ground return	B1	GND	Ground return



RECOMMEND P.C.B LAYOUT (COMPONENT SIDE)
 TOLERANCE FOR PCB LAYOUT IS ± 0.05
 KEEP OUT AREA

PART NO.: SEE THE PART NUMBER CODE		GOLDCONN TECHNOLOGIES COMPANY LIMITED		DRAWN BY SAM	DATE 2021.08.12
QUALITY SYMBOL 0 0 0 0 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		TITLE USB 3.1 C TYPE FEMALE SINK CH.0.78 沉板2.36 SHORT SMT+DIP L 7.95		
	x.xxxx	± ---	DWG.NO. CF324-019-75		SHEET NO. 2 OF 2
	x.xxx	± 0.10	SCALE 1:1		
	x.xx	± 0.25	DIMENSION STYLE MM ONLY		
	x.x	± 0.30	DESIGN UNITS METRIC		
ANGULAR	± ---°	APPROVED BY JACKY			DATE 2021.08.12
			THIRD ANGLE PROJECTION		